Docket No.

250061US2S DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Shinsuke SAKAMOTO, et al.

SERIAL NO: New Divisional Application

GAU:

FILED:

Herewith

EXAMINER:

FOR:

nciewiui Exalviinek.

METHOD

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

SEMICONDUCTOR INTEGRATED CIRCUIT DEVICE AND STANDARD CELL PLACEMENT DESIGN

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

- The Applicants wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references were submitted in prior Application Serial No. 10/282,144, filed October 29, 2002, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

- Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.
- ☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

- ☐ Each item of information contained in this information disclosure statement was first cited in any communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of this statement.
- □ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number <u>15-0030</u>. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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Form PTO 1449	U.S. DEPARTMENT OF COMMERCE			ATTY DOCKET NO.		SERIAL NO.		
(Modified)		PATENT AND TRAC	EMARK OFFICE	250061US2S DIV		New Divisional Application		
				APPLICANT				
LIST OF	REFE	RENCES CITED BY AP	PLICANT	Shinsuke SAKAMOTO, et al.				
				FILING DATE		GROUP		
				Herewith				
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE	
	AA	4,161,662	7/17/79	Malcolm et al.]			
	AB	4,661,815	4/28/87	Takayama et al.				
	AC	4,928,160	5/22/90	Crafts				
	AD	5,021,856	6/4/91	Wheaton			***	
	ΑE	6,525,350	2/25/03	Kinoshita et al.				
	AF	6,410,972	6/25/02	Sei et al.				
	AG	5,936,868	8/10/99	Hall				
	АН	5,369,596	11/29/94	Tokumaru				
	AI						<u></u>	
	AJ							
	AK							
	AL							
	AM							
	AN							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY	NTRY		TRANSLATION YES NO	
	AO	11-214662	8/6/99	Japan			Х	
	AP	2000-269346	9/29/00	Japan			Х	
	AQ							
	AR							
	AS							
	AT		-					
	ΑU							
	AV							
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)								
	AW	Kasem, M.; "A new generation of interconnect technology for high performance eletronics," Electronics Manufacturing Technology Symposium, 1999. Twenty-Fourth IEEE/CPMT, 18-19 Oct. 1999, Pages 440-447						
	AX							
	AY							
	AZ				Addi	tional Refe	erences sheet(s) attached	
Examiner					Date Considered			
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								